(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
28 June 2012 (28.06.2012)

WIPO | PCT

(10) International Publication Number
WO 2012/087107 A1

(51) International Patent Classification:
H05K 7/20 (2006.01) *H05K 1/03* (2006.01)

(21) International Application Number:
PCT/MY2011/000096

(22) International Filing Date:
16 June 2011 (16.06.2011)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
12/977,595 23 December 2010 (23.12.2010) US
PI 2011000669 14 February 2011 (14.02.2011) MY

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(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

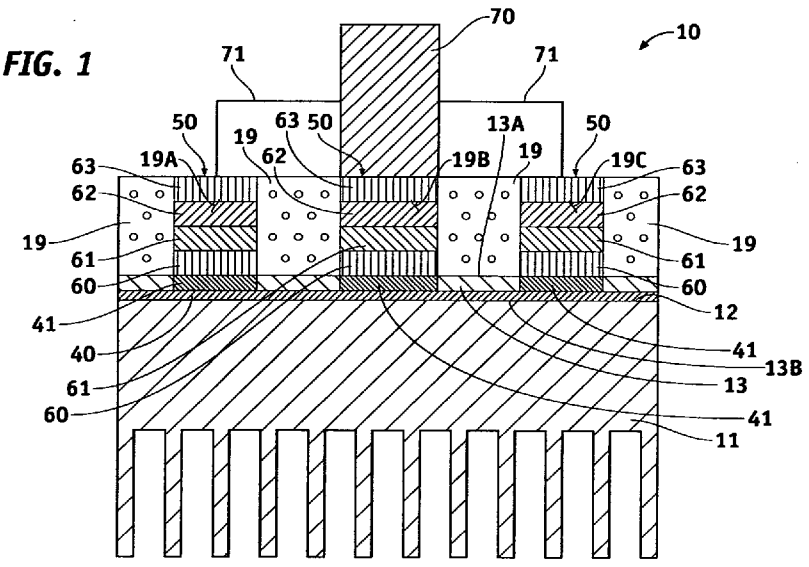
— *of inventorship (Rule 4.17(iv))*

Published:

— *with international search report (Art. 21(3))*

(54) Title: INTEGRATED PLATED CIRCUIT HEAT SINK AND METHOD OF MANUFACTURE

FIG. 1



(57) Abstract: A method of preparing a non-ferrous metal substrate for plating includes providing an anodized layer on an aluminum substrate and electrically isolating the anodized layer from the non-ferrous metal substrate by applying an electrically non-conductive micro-filler to the anodized layer to form a filled region of the anodized layer electrically isolating the anodized layer from the non-ferrous metal substrate.

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